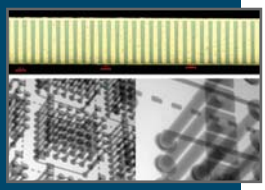
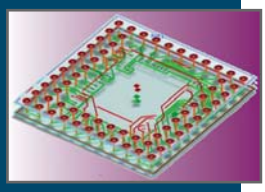
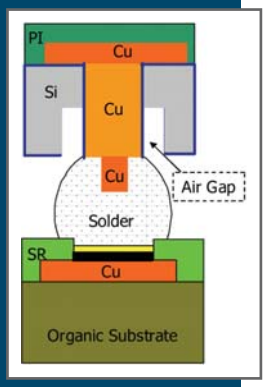
Advanced Packaging Update:

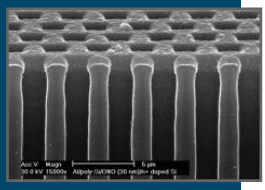
Market and Technology Trends

Vol. 1-010









This volume of the Advanced Packaging Update features special coverage of the developments in silicon interposers. Silicon substrates and interposers have been explored many times over the last 20 years, but never met expectations. With the impetus of through-silicon via (TSV) development, they are being considered again. This report evaluates the market for silicon interposers and discusses how the technology has developed so that they may be more successful this time. Information from suppliers of interposers, users, and assembly houses is included in the report. The report also examines economic trends and the impact on the semiconductor industry. IC package subcontractors are reporting increased capacity utilization. Plans for CAPEX spending in 2010 are compared with actual 2009 expenditures.

Table of Contents

List of Figures

Select List of Tables

Annual subscription – $3,425 (4 issues)
Single issue – $975

TechSearch INTERNATIONAL
4801 Spicewood Springs Road • Suite 150
Austin, Texas 78759
Tel: 512-372-8887 • Fax: 512-372-8889
tsi@techsearchinc.com • www.techsearchinc.com